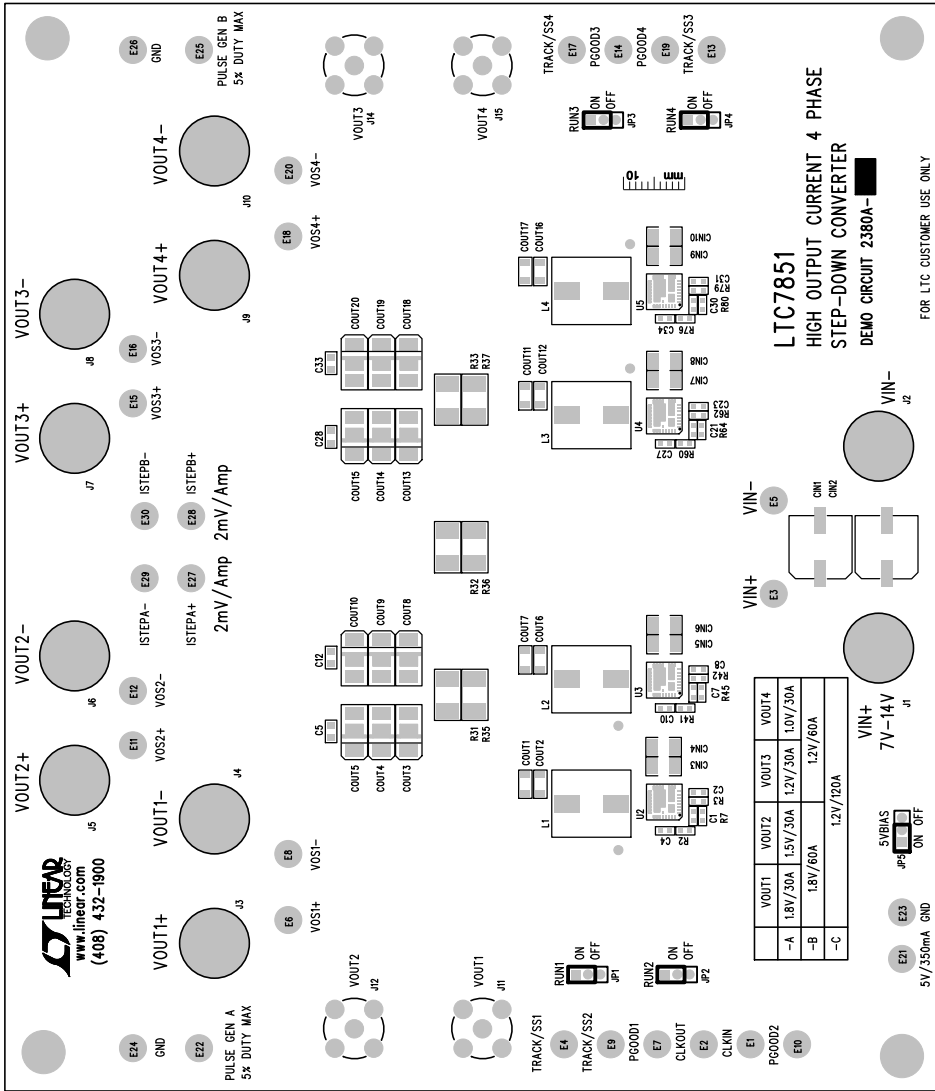


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	1	PRODUCTION	Mike S.
			DATE
			10-21-15



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:

TOP SIDE
BOTTOM SIDE
4X STANDOFF, NYLON, SNAP ON.

8. The GND pad on the LTC7851 footprint at U1 is oversized.
Refer to the data sheet for the correct dimensions.

APPROVALS		LTC7851	
PCB DES.	HZ	DATE	10-21-15
APP. ENG.	Mike S.	TITLE: TOP ASSEMBLY DRAWING	
		HIGH OUTPUT CURRENT 4 PHASE STEP-DOWN CONVERTER	
SCALE = NONE		SIZE	IC NO. LTC7851EUHH
			REV. 1
			DEMO CIRCUIT 2380A
			FILENAME: DC2380B1PCB
			SHT 1 OF 2